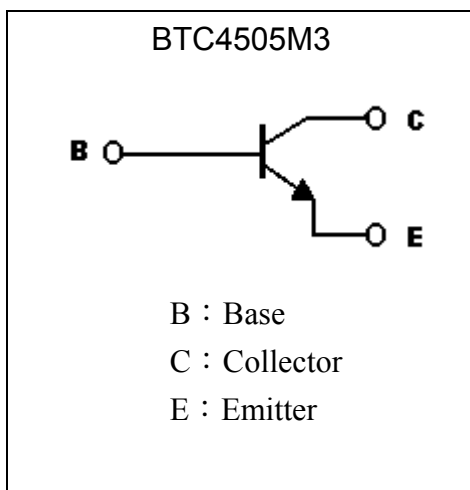
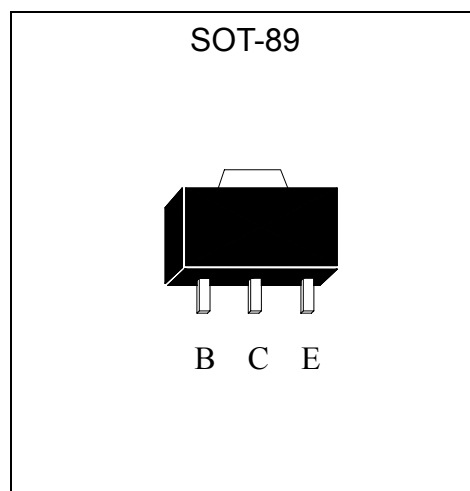


High Voltage NPN Epitaxial Planar Transistor

BTC4505M3

Features

- High breakdown voltage. ($BV_{CEO}=400V$)
- Low saturation voltage, typically $V_{CE(sat)}=0.1V$ at $I_C/I_B=10mA/1mA$.
- Complementary to BTA1759M3
- Pb-free package

Symbol

Outline

Absolute Maximum Ratings ($T_a=25^{\circ}C$)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V_{CBO}	400	V
Collector-Emitter Voltage	V_{CEO}	400	V
Emitter-Base Voltage	V_{EBO}	6	V
Collector Current	I_C	300	mA
Power Dissipation	P_d	600	mW
Junction Temperature	T_j	150	$^{\circ}C$
Storage Temperature	T_{stg}	-55~+150	$^{\circ}C$

**Characteristics** (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV _{CB0}	400	-	-	V	I _C =50μA, I _E =0
BV _{CEO}	400	-	-	V	I _C =1mA, I _B =0
BV _{EBO}	6	-	-	V	I _E =50μA, I _C =0
I _{CB0}	-	-	10	μA	V _{CB} =400V, I _E =0
I _{EBO}	-	-	10	μA	V _{EB} =6V, I _C =0
*V _{CE(sat)}	-	0.1	0.5	V	I _C =10mA, I _B =1mA
*V _{BE(sat)}	-	-	1.5	V	I _C =10mA, I _B =1mA
h _{FE}	82	-	270	-	V _{CE} =10V, I _C =10mA
f _T	-	20	-	MHz	V _{CE} =10V, I _C =10mA, f=100MHz
Cob	-	7	-	pF	V _{CB} =10V, f=1MHz

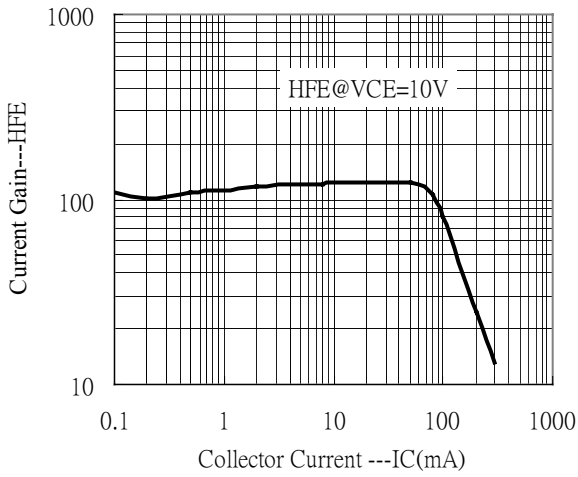
*Pulse Test : Pulse Width ≤380μs, Duty Cycle ≤2%

Ordering Information

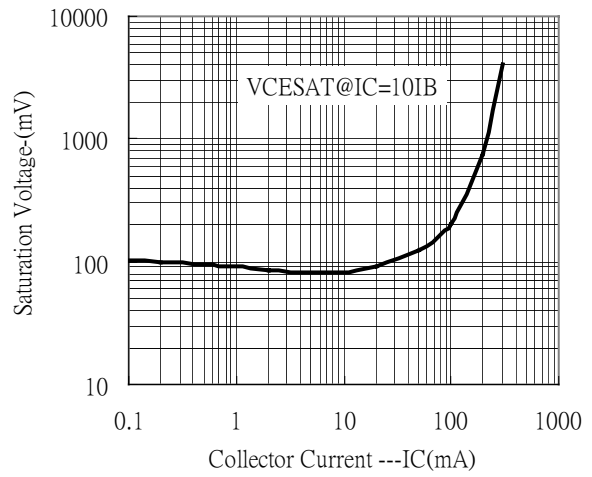
Device	Package	Shipping
BTC4505M3	SOT-89 (Pb-free)	1000 pcs / Tape & Reel

Characteristic Curves

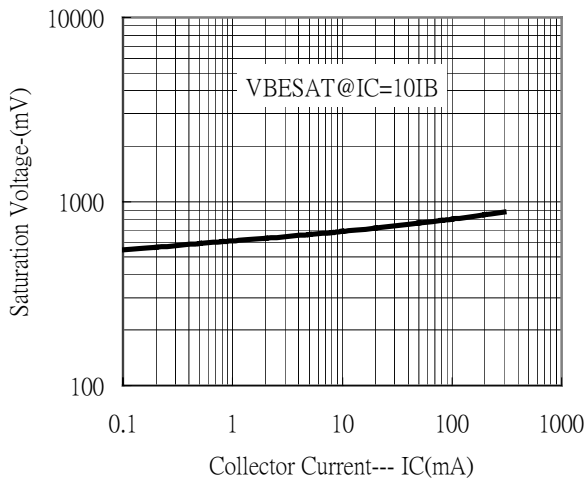
Current Gain vs Collector Current



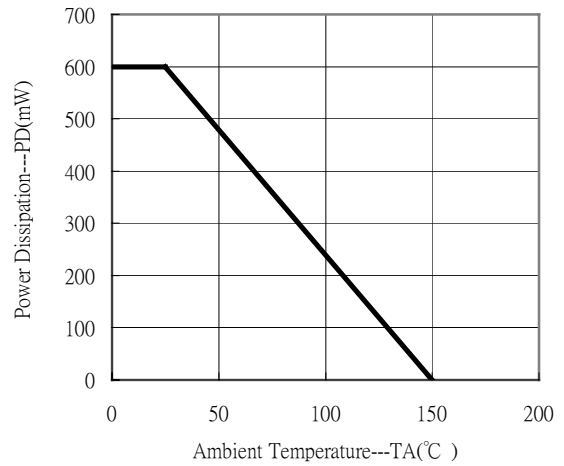
Saturation Voltage vs Collector Current



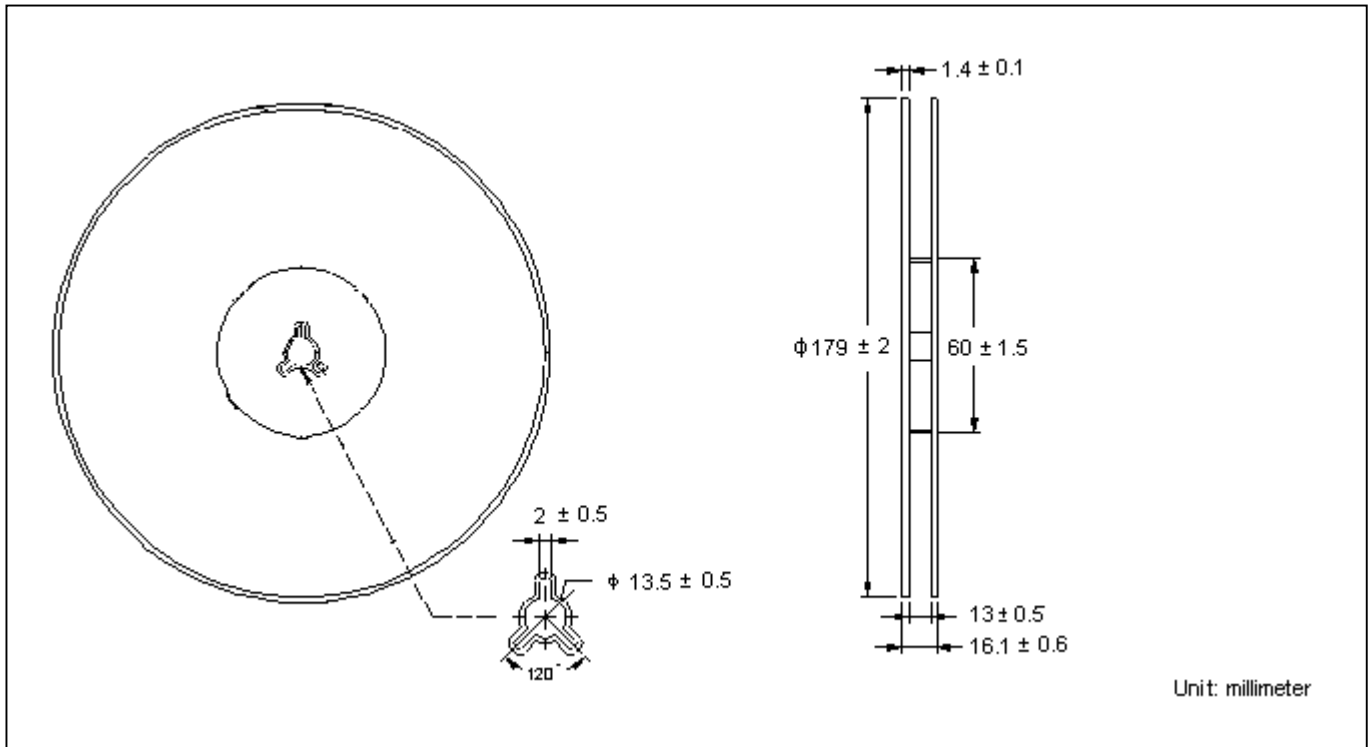
Saturation Voltage vs Collector Current



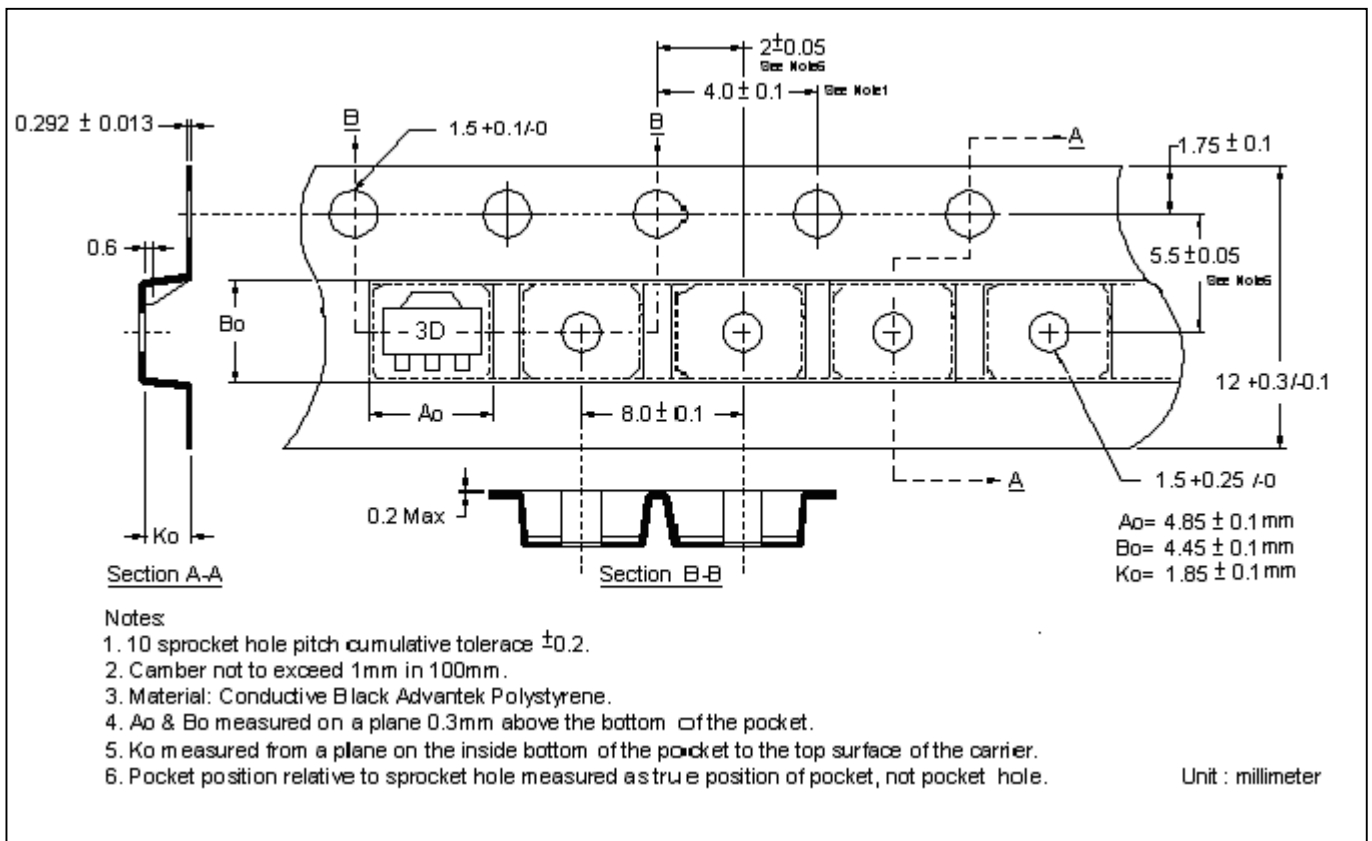
Power Derating Curve



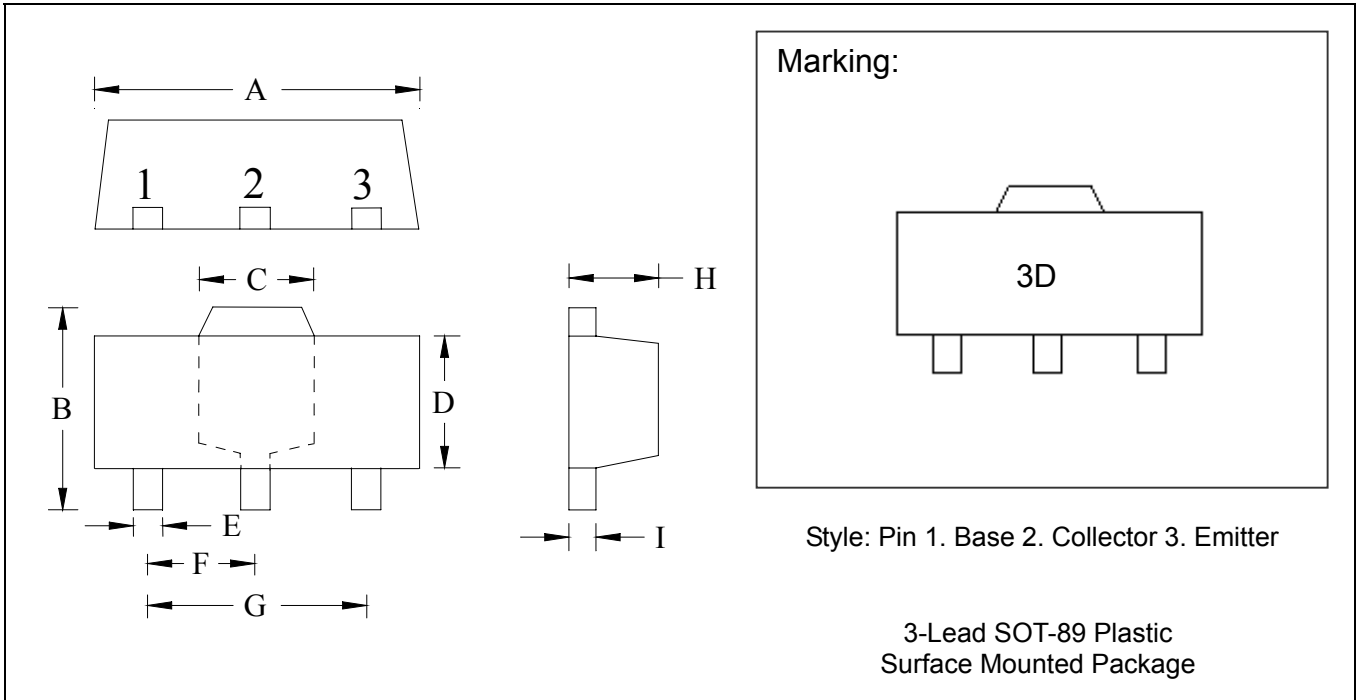
Reel Dimension



Carrier Tape Dimension



SOT-89 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0583	0.0598	1.48	1.527
B	0.1594	0.1673	4.05	4.25	G	0.1165	0.1197	2.96	3.04
C	0.0591	0.0663	1.50	1.70	H	0.0551	0.0630	1.40	1.60
D	0.0945	0.1024	2.40	2.60	I	0.0138	0.0161	0.35	0.41
E	0.01417	0.0201	0.36	0.51					

Notes: 1.Controlling dimension: millimeters.
 2.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3.If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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